

### Claim Amendments

1-14 (Canceled)

15. (Currently Amended) A head gimbal assembly (HGA) for supporting a ~~slider/magnetic recording (MR) head in a disc drive, the slider/MR head including opposing front and back side, the front side defining an air bearing surface,~~ comprising:

a suspension ~~supporting the slider/MR head;~~

a head interconnect circuit being attached to and disposed along the suspension, the head interconnect circuit including a first conductive material; and

a slider ~~scale package for electrically coupling the slider/MR head to the head interconnect circuit, the slider scale package comprising the slider/MR head, a top, a bottom; and~~

a flex circuit having a first and second surface, the first surface attached to the top back of the slider/MR head, and at least one interconnect pad disposed on the second surface of the flex circuit back of the slider/MR head and for providing electrical contact with the conductive material of the head interconnect circuit.

16. (Currently Amended) The head gimbal assembly HGA of claim 15, wherein the slider/MR head includes a front end and at least one bond pad disposed on the front end, and the flex circuit further includes a second conductive material extending between the at least one bond pad and the at least one interconnect pad, and the conductive material of the flex circuit is electrically connected to the at least one interconnect pad and to the at least one bond pad.

17. (Currently Amended) The head gimbal assembly HGA of claim 16, wherein the slider ~~scale package assembly~~ includes first, second, third, and fourth interconnect pads disposed on the back of the slider/MR head, and first, second, third, and fourth bond pads disposed on the front end of the slider/MR head, wherein the at least one interconnect pad is one of the first, second, third or fourth interconnect pads, and the at least one bond pad is one of the first, second, third or fourth bond pads.

18. (Currently Amended) The head gimbal assembly HGA of claim 17, wherein the first and second bond pads are electrically coupled to a first pair of positive and negative polarities of the slider/MR head for reading data, respectively, and the third and fourth bond pads are electrically coupled to a second pair of positive and negative polarities of the slider/MR head for writing data, respectively, and the first, second, third, and fourth interconnect pads are arranged such that the polarities of the bond pads match with polarities from the interconnect pads.

19-33 (Canceled)

34. (New) A head gimbal assembly comprising:

- a suspension, the suspension having a plurality of first conductive material;

- a slider having a top and a bottom;

- a flex circuit having a first and second surface, wherein the first surface positioned on the top of the slider, further, wherein the flex circuit has a plurality of second conductive material positioned on the second surface; and

- at least one interconnect pad disposed between the plurality of first conductive material and the plurality of second conductive material to establish an electrical connection.

35. (New) The head gimbal assembly of claim 34, wherein the slider further includes at least one bond pad, wherein the bond pad provides for an electrical connection to a transducer positioned in the slider.

36. (New) The head gimbal assembly of claim 35, wherein said plurality of second conductive material extends and is electrically connected to said bond pad.

37. (New) The head gimbal assembly of claim 35, wherein the slider further includes a front end, further wherein said bond pad is positioned on said front end.

38. (New) The head gimbal assembly of claim 35, wherein the slider includes first, second, third, and fourth interconnect pads disposed on the back of the slider/MR head, and first, second, third, and fourth bond pads disposed on the front end of the

slider/MR head, wherein the at least one interconnect pad is one of the first, second, third or fourth interconnect pads, and the at least one bond pad is one of the first, second, third or fourth bond pads.

39. (New) The head gimbal assembly of claim 38, wherein the first and second bond pads are electrically coupled to a first pair of positive and negative polarities of the slider/MR head for reading data, respectively, and the third and fourth bond pads are electrically coupled to a second pair of positive and negative polarities of the slider/MR head for writing data, respectively.

40. (New) The head gimbal assembly of claim 39, wherein the first, second, third, and fourth interconnect pads are arranged such that the polarities of the bond pads match with polarities of the interconnect pads.

41. (New) The head gimbal assembly of claim 40, wherein the first and second interconnect pads are electrically connected to the first and second bond pads of the slider, respectively, and the third and fourth interconnect pads are electrically connected to the third and fourth bond pads of the slider, respectively.